

LISTING OF CLAIMS

1. (Original) A flip chip package comprising:
a semiconductor chip having a first side and a second side opposing the first side;
a circuit substrate electrically connected to the first side of the semiconductor chip;
a protective cap disposed over the second side of the semiconductor chip, the protective cap including at least one portion extending beyond an edge of the semiconductor chip.

2. (Original) The flip chip package of claim 1, wherein the protective cap includes metal.

3. (Original) The flip chip package of claim 2, wherein the protective cap is made of one selected from the group consisting of copper (Cu), copper alloy, aluminum (Al), and aluminum alloy.

4. (Original) The flip chip package of claim 1, further comprising:
a plurality of solder bumps to electrically connect the semiconductor chip and the circuit substrate.

5. (Original) The flip chip package of claim 4, further comprising:
a molding resin layer sealing the electrical connection between the semiconductor chip and the circuit substrate.

6. (Withdrawn) The flip chip package of claim 1, further comprising:
a plurality of bonding wires to electrically connect the semiconductor chip and the circuit substrate.
7. (Withdrawn) The flip chip package of claim 6, further comprising:
a molding resin layer sealing the electrical connection between the semiconductor chip and the circuit substrate.
8. (Original) The flip chip package of claim 1, further comprising:
an adhesion layer disposed between the second side of the semiconductor chip and the protective cap.
9. (Original) The flip chip package of claim 1, further comprising:
a molding resin layer sealing the electrical connection between the semiconductor chip and the circuit substrate.
10. (Original) The flip chip package of claim 9, wherein the molding resin layer engages the extended portion of the protective cap.

11. (Original) The flip chip package of claim 9, wherein the molding resin layer at least assists in mounting the protective cap over the second side of the semiconductor chip.

12. (Original) The flip chip package of claim 9, wherein the protective cap includes a dovetail groove in the extended portion; and the molding resin layer includes a dovetail portion disposed in the dovetail groove.

13. (Original) The flip chip package of claim 1, further comprising: a molding resin layer that engages the protective cap.

14. (Original) The flip chip package of claim 1, further comprising: a molding resin layer that at least assists in mounting the protective cap over the second side of the semiconductor chip.

15. (Original) The flip chip package of claim 1, further comprising: a molding resin layer including a dovetail portion; and wherein the protective cap includes a dovetail groove in the extended portion with the dovetail portion of the molding resin layer disposed therein.

16. (Original) The flip chip package of claim 1, further comprising:

solder balls formed on a surface of the circuit substrate opposite a surface to which the circuit substrate is electrically connected to the semiconductor chip.

17-30. (Canceled)